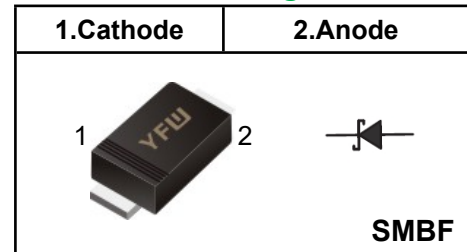


Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 100 V
Forward Current - 3 A
FEATURES

- ◆Metal silicon junction, majority carrier conduction
- ◆For surface mounted applications
- ◆Low power loss, high efficiency
- ◆High forward surge current capability
- ◆For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- ◆Lead free in comply with EU RoHS 2011/65/EU directives


Pinning

Marking Code

SSL310BF	SL310B
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MECHANICAL DATA

- ◆Case: SMBF
- ◆Terminals: Solderable per MIL-STD-750, Method 2026
- ◆Approx. Weight: 57mg /0.002oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 ° ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SSL310BF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	70	V
Maximum DC Blocking Voltage	V_{DC}	100	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	I_{FSM}	80	A
Maximum Instantaneous Forward Voltage at 3 A	V_F	0.6	V
Maximum Instantaneous Reverse Current at Rated DC Reverse Voltage <small>$T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$</small>	I_R	0.1	mA
Typical Junction Capacitance ⁽¹⁾	C_j	160	pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	60	°C/W
Operating Junction Temperature Range	T_j	-55 ~ +150	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2" X 2" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

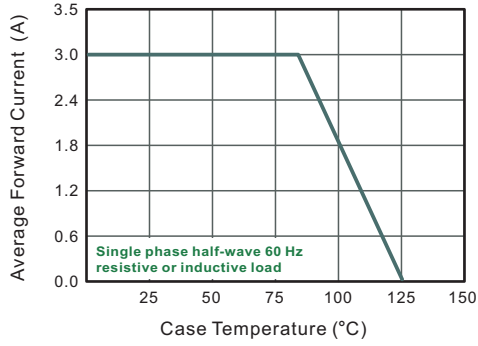


Fig.2 Typical Reverse Characteristics

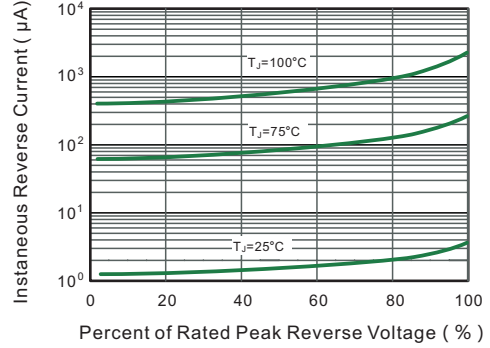


Fig.3 Typical Forward Characteristic

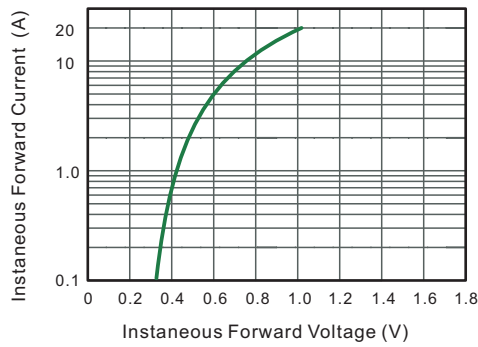


Fig.4 Typical Junction Capacitance

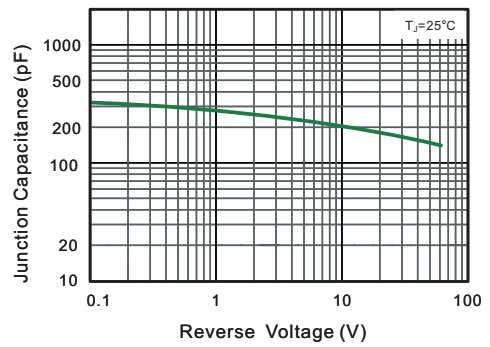


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

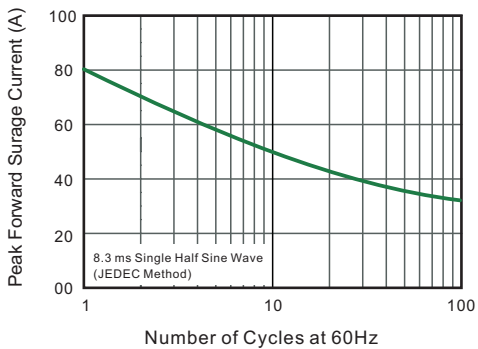
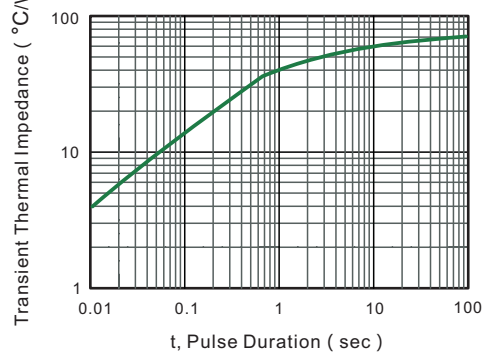


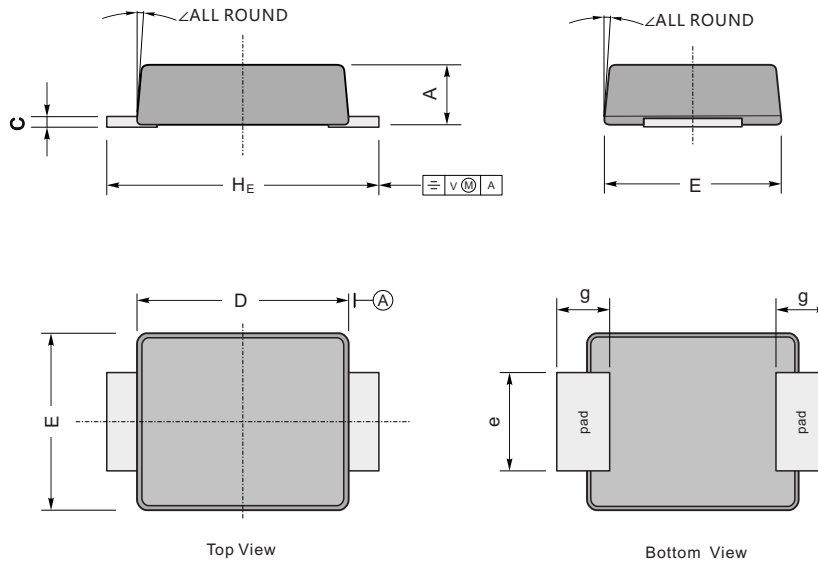
Fig.5- Typical Transient Thermal Impedance



Package Outline

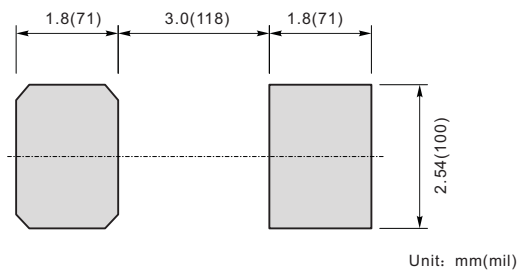
SMBF

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	H _E	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86		
	min	43	7	165	138	200	75		

The recommended mounting pad size



Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMBF	Tape/Reel, 13" reel	5000	EIA-481-1